



Experimental results and Finite Element Analysis of single REBCO tape and TSTC conductor for high field magnets

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School of
Engineering



Plasma Science and Fusion Center





Outline

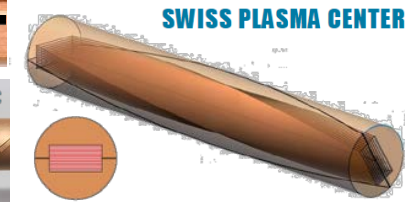
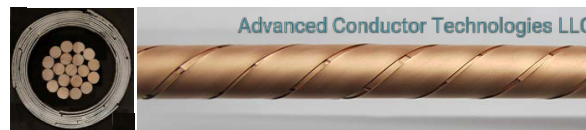
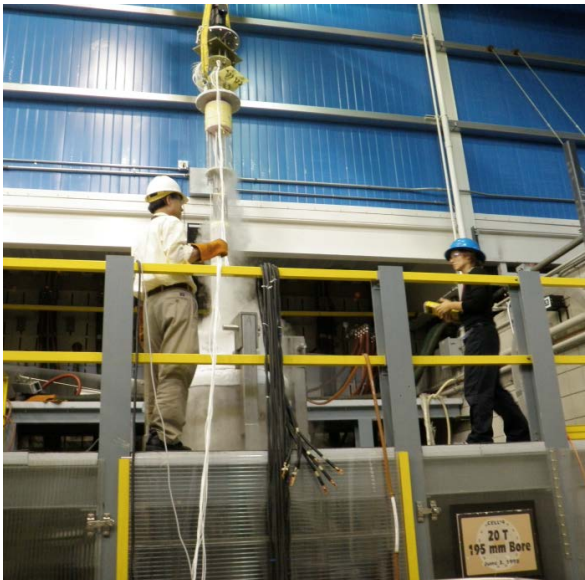
- Research activities and their importance
- Experiments on single tapes and TSTC conductors
- Modeling work on tapes and cables
 - Torsion, Bending and Lorentz load
- Next high field TSTC experiment
- TSTC conductor scale-up
- Joints and AC losses
- Future directions and conclusions



Introduction

Complementary research activities of Tufts and MIT-PSFC:

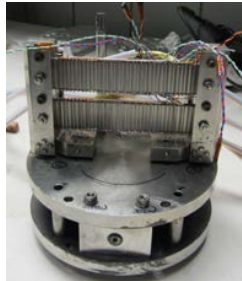
- Characterization of the electrical and mechanical behaviors of HTS materials under loads relevant to magnets using *custom-made experimental devices* and *finite element analysis* (FEA) techniques in support of design and fabrication of the next generation high-field HTS magnets.
- *Development, fabrication and high-field, high-current experiments of the Twisted Stacked-Tape Cable (TSTC).*



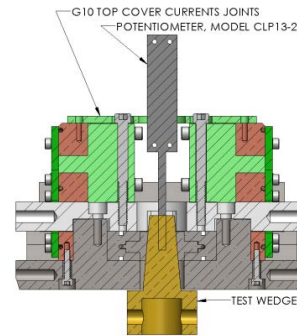


What do we do?

Pure bending Nb_3Sn



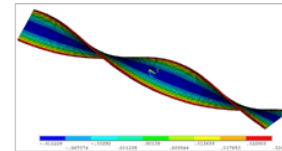
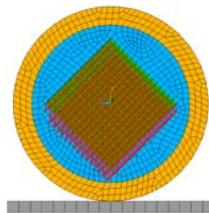
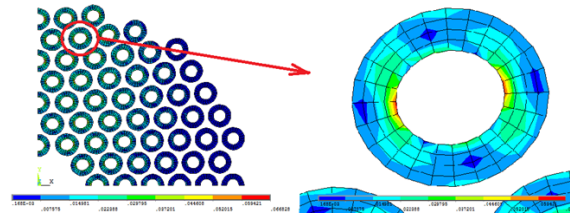
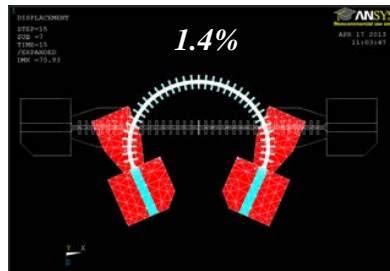
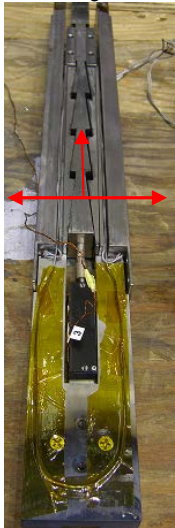
Transverse load Nb_3Sn



Electromechanical characterization HTS



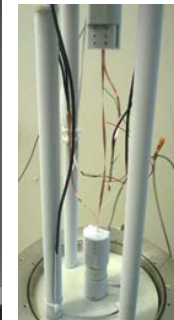
Transverse load Nb_3Sn



HTS Conductor Electro-Magnetic load



HTS Conductor bending



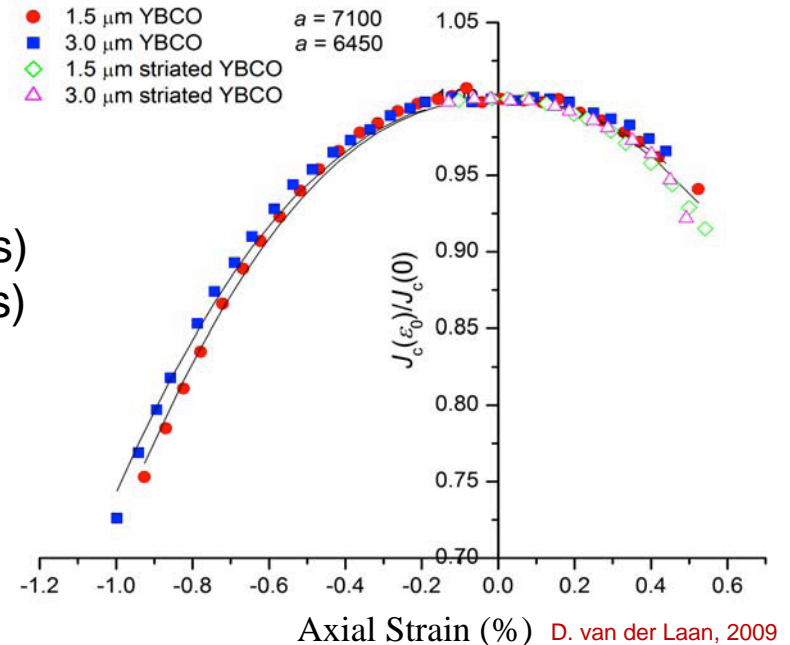
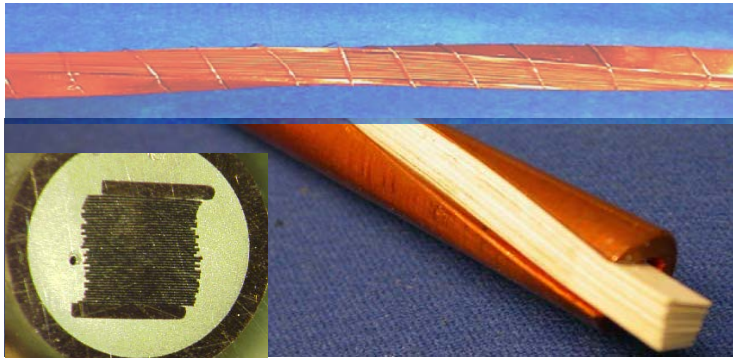
Torsion-Tension HTS



Our approach

The *critical current* of a superconductor is a function of *load* (stress & strain). For high field magnet applications the conductor will experience a variety of different loads during *cable and magnet fabrication, thermal cool down, and magnet operation*:

- *Axial* (different rates of thermal contraction)
- *Torsion* (twisting during cable fabrication)
- *Bending* (winding of magnet coils)
- *Transverse compression* (electromagnetic forces)
- *Combined tension-torsion* (magnetic hoop stress)



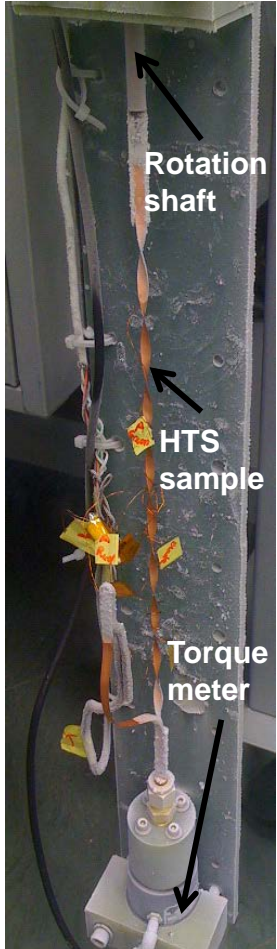
We are particularly interested in *HTS TSTC conductor* to be used in the next generation high-field magnets.

Our work allowed us to identify key features of TSTC for twisting, bending and transverse load.

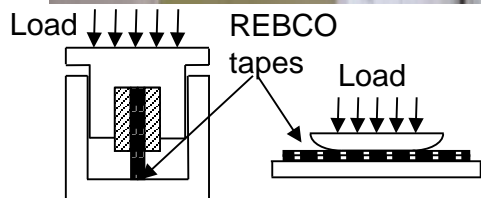
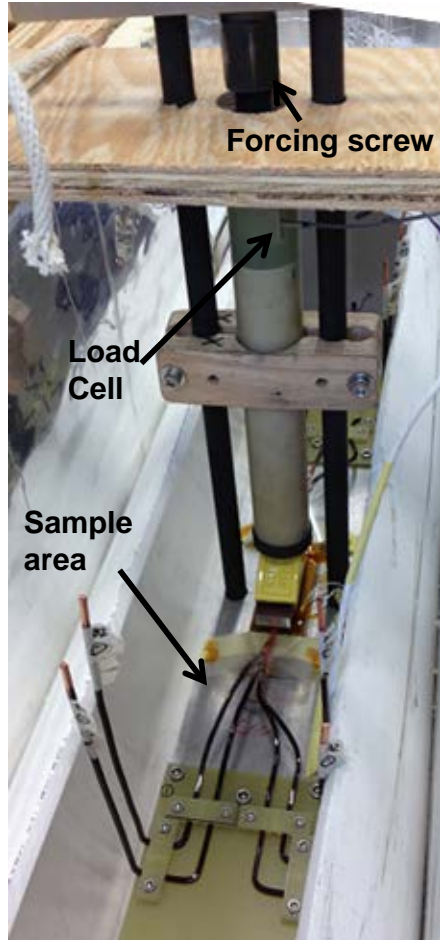


Experiments on REBCO tapes

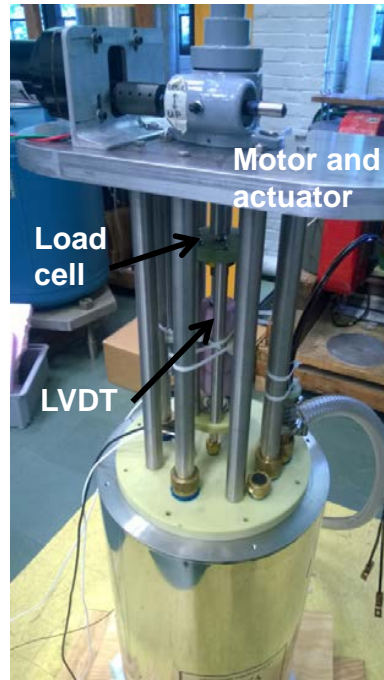
I. Pure Torsion



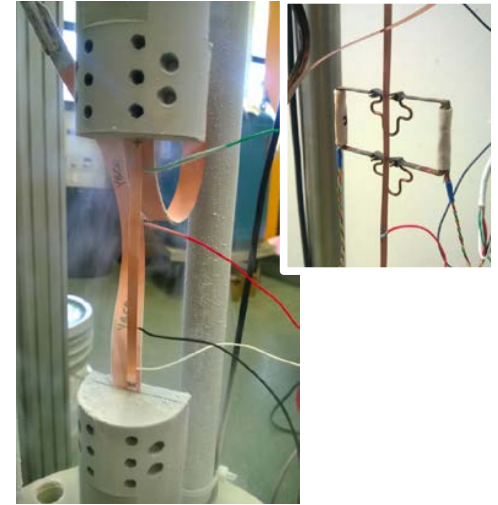
II. Mechanical Transverse Compression



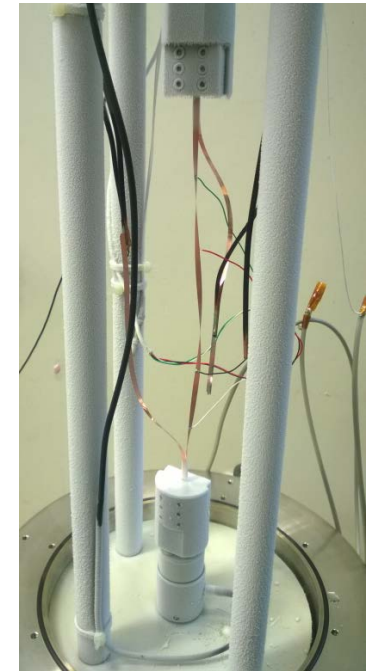
III. Tension



a. Tension



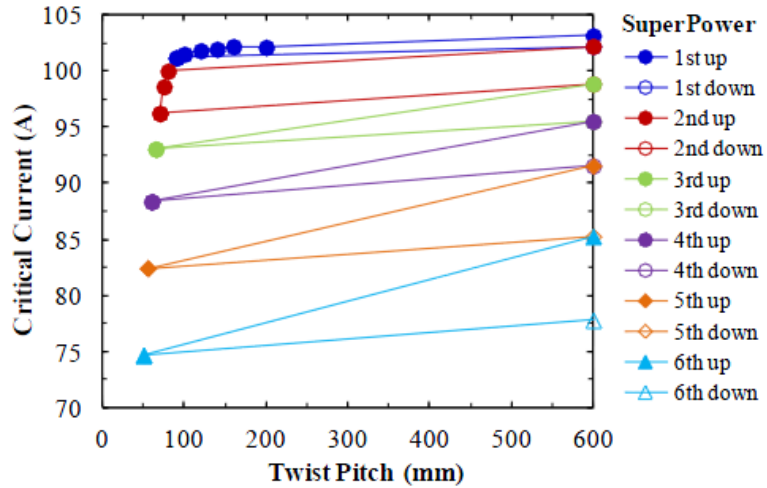
b. Tension-Torsion



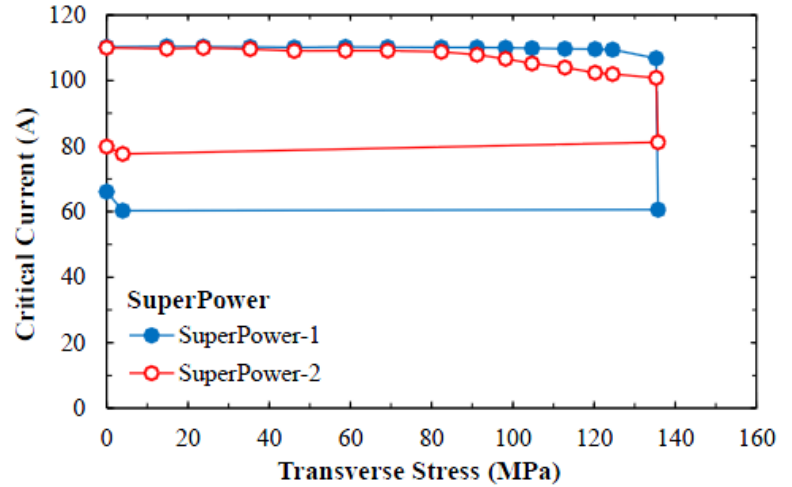


Experiments on REBCO tapes

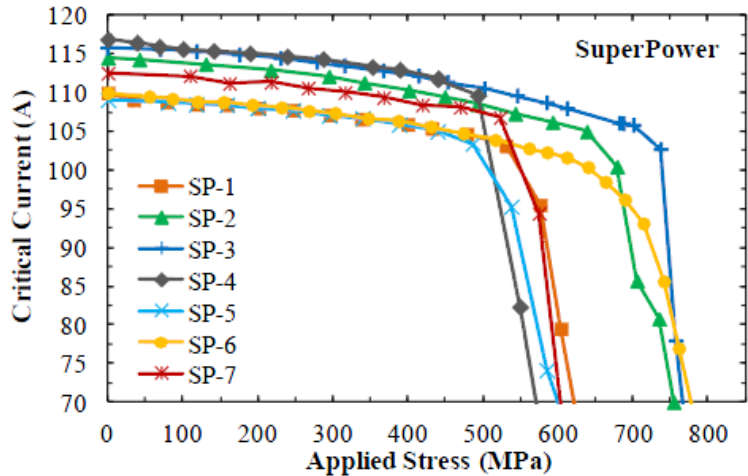
I. Pure Torsion



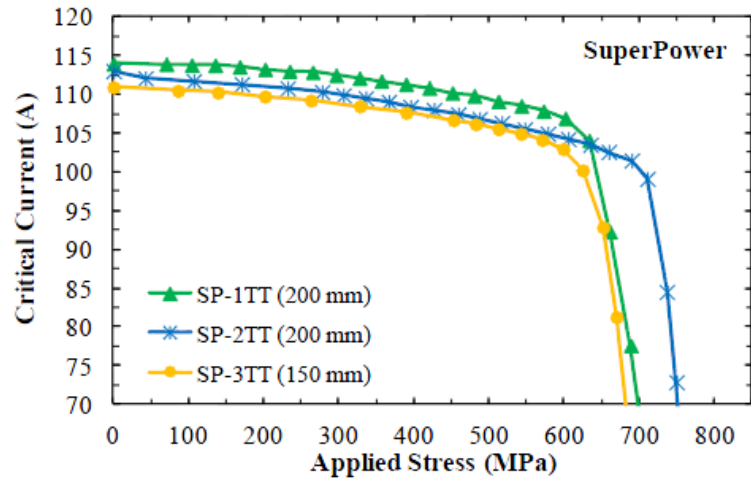
II. Mechanical Transverse Compression (Thin Edge)



III.a Tension



III.b Tension-Torsion

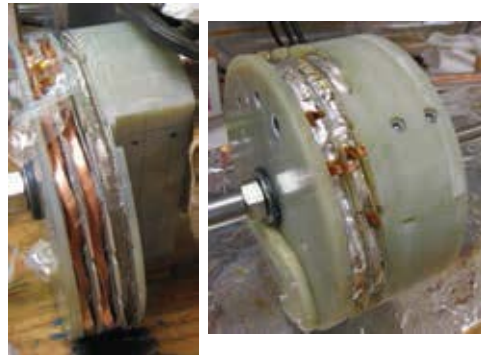
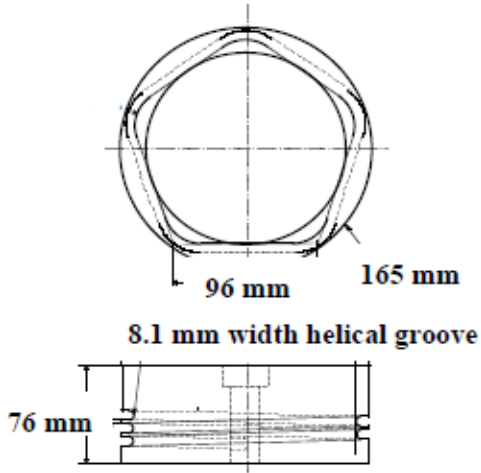




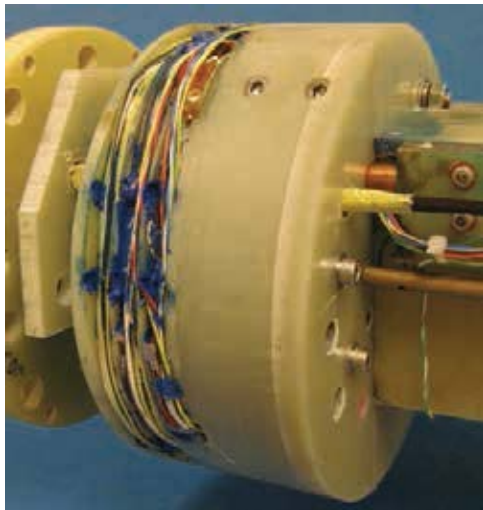
Experiments on TSTC conductors

Pentagon Stacked-Tape Twist-Wind (STTW) Sample

40-Tape, 2.6 Turn, 2.6 m cable ~200 mm twist pitch
REBCO tape: SuperPower 4 mm width, 0.1 mm thick, 120 A at 77 K



Stacked-tape cable **twisted during winding** in a groove covered with **braided copper**.



Soldered, and then filled with **Stycast** around the braided copper.

Sample current DC power supply of 10 kA (seven small power supplies in parallel)

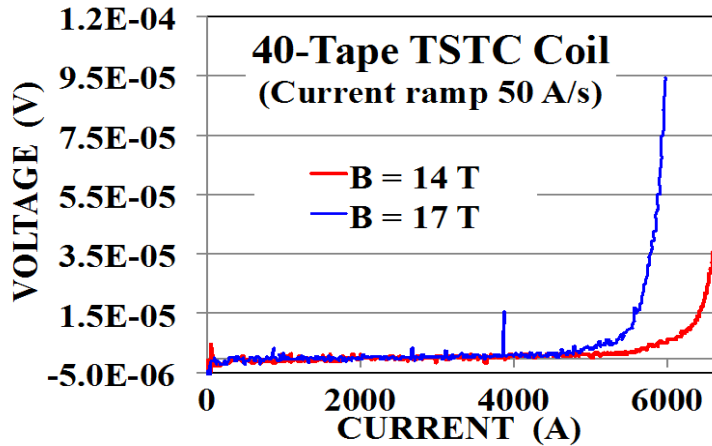


17 T Bitter magnet

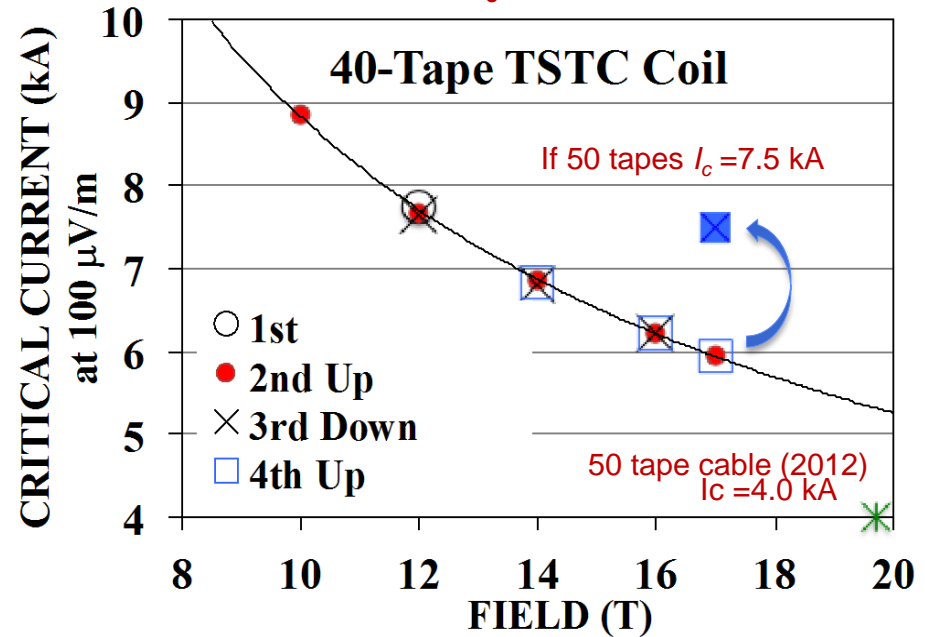


Experiments on TSTC conductors

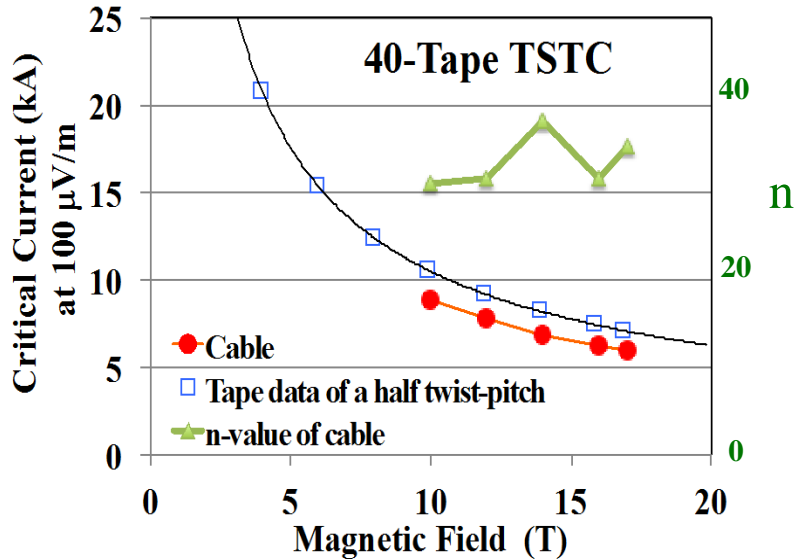
I-V curves



B - I_c results

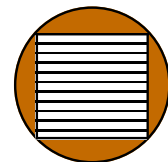


Comparison with tape data



- The degradation compared to single tape data was **16%** [16%, between 10 T and 17 T]
- High n-value
- **No cyclic load effect** (102 kN/m)

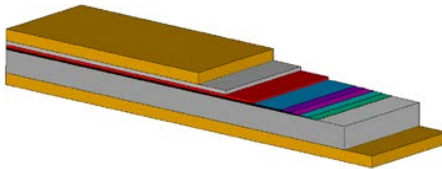
J_e (8.1 mm Dia.) = 117 A/mm²
 J_e (4 mmx4mm) = 375 A/mm²
 J_e (5.7 mm Dia.) = 239 A/mm²



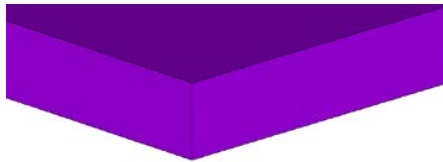


Modeling

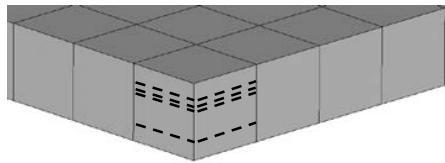
Structural *finite element analysis* **ANSYS**



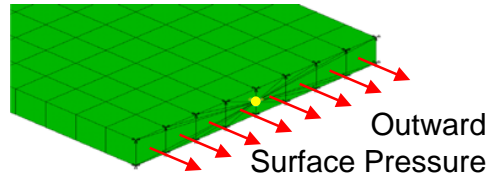
Single homogenous volume



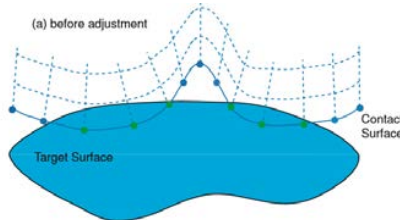
One element in thickness



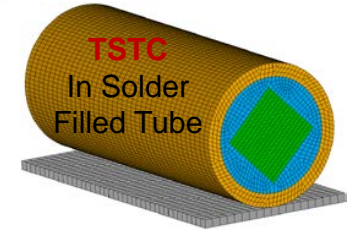
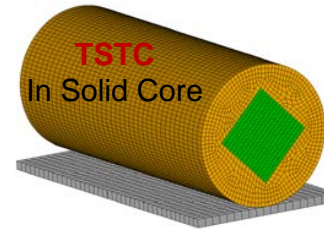
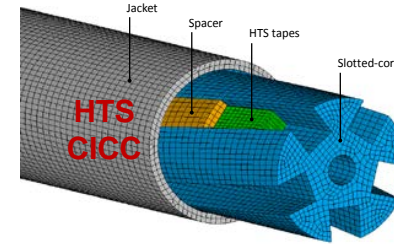
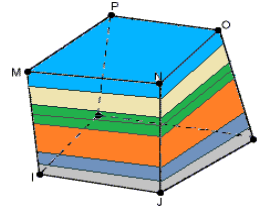
Multipoint Coupling Constraint



Surface-to-Surface *Contact Pairs*

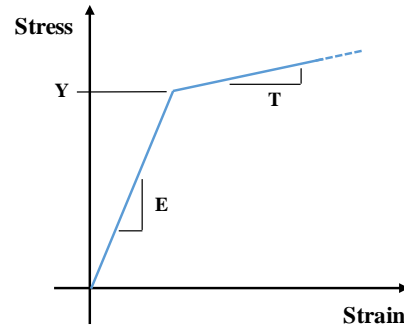


SOLSH190 – 3D 8-node structural *solid-shell element* with layered capabilities



Bilinear Material Properties

Material		E (GPa)	Y (MPa)	T (GPa)
Substrate	Hastelloy® C-276	180	1225	7.5
	Stainless Steel	190	850	10.0
	Ni-5AT.%W	120	225	3.75
Copper	Electroplated	85	350	4.0
	Rolled	120	455	4.5
Silver		90	225	22.0
REBCO/Buffer		150	---	---
Aluminum		80	235	15.0
Copper		120	400	4.5
Solder (Sn60/Pb40)		30	40	0.1

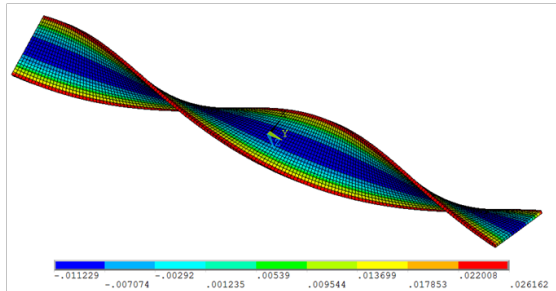




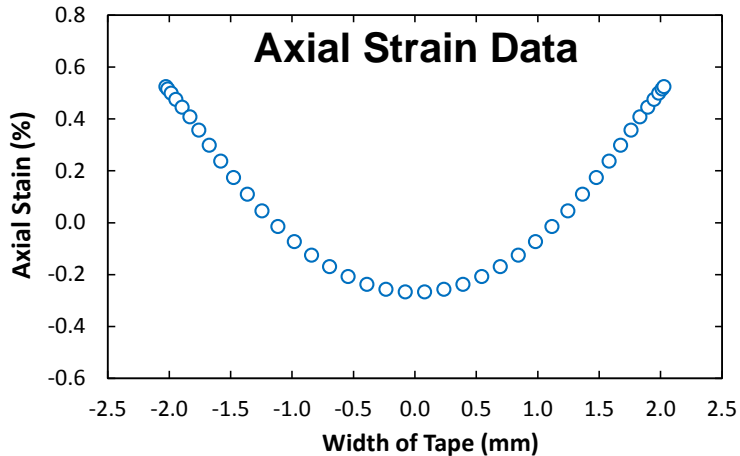
Predicting I_c using FEA strain results

We can estimate *critical current* of tape using *axial strain* through width of tape

Numerical Model



Axial Strain Data

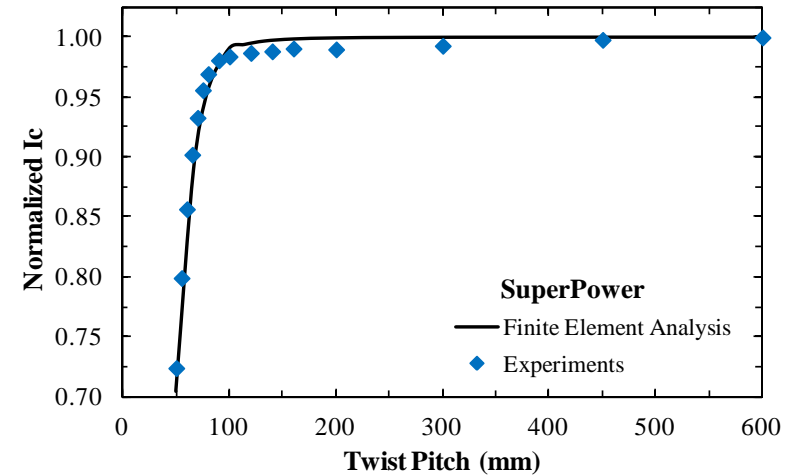
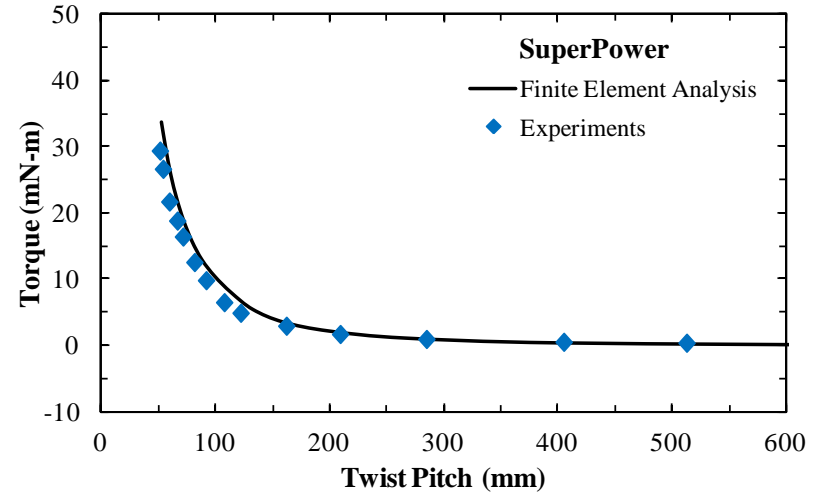


Analytical Relationship

$$I_c = t_s \int_{-\frac{w}{2}}^{\frac{w}{2}} j_c(\epsilon_x) dx \quad j_c(\epsilon) = I_c(\epsilon)/(t_s w)$$

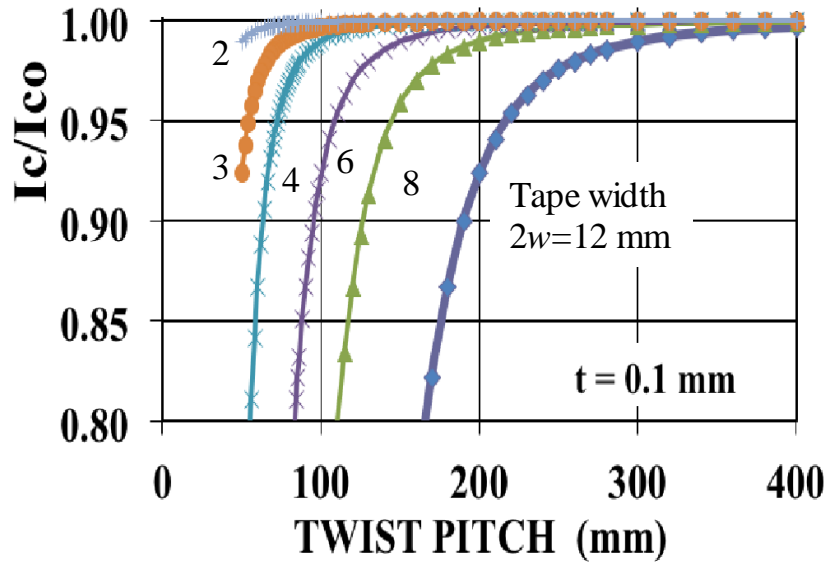
$$\frac{I_c}{I_{c0}} = 0.057713 \times 10^{12} \epsilon_{b\theta}^6 - 0.03979215 \times 10^{10} \epsilon_{b\theta}^5 - 0.2090279 \times 10^8 \epsilon_{b\theta}^4 + 0.02385557 \times 10^6 \epsilon_{b\theta}^3 - 0.1668065 \times 10^4 \epsilon_{b\theta}^2 - 0.003662115 \times 10^2 \epsilon_{b\theta} + 1.0$$

Experimental Data
 D. van der Laan, 2009



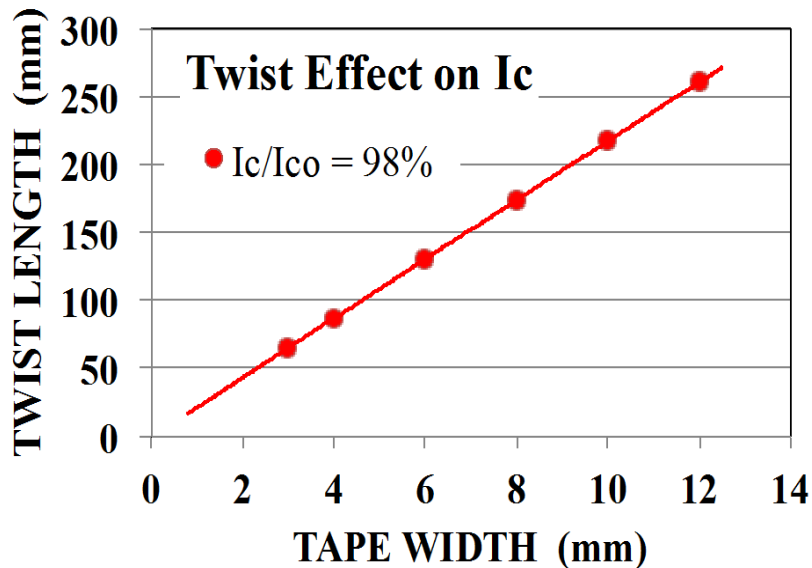


Twisting of tapes with different widths



I_c Degradation due to Twisting
 (analytical evaluation)

$$\varepsilon_x = \frac{\theta^2}{2} \left(x^2 - \frac{w^2}{3} \right)$$



Tape-Width Dependence
 (analytical evaluation)

Twist-pitch $L_p (I_c/I_{co} = 0.98) \approx 22 \cdot 2w$ (mm)
 2w tape width

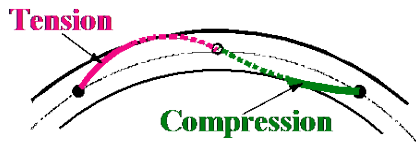


Bending behavior

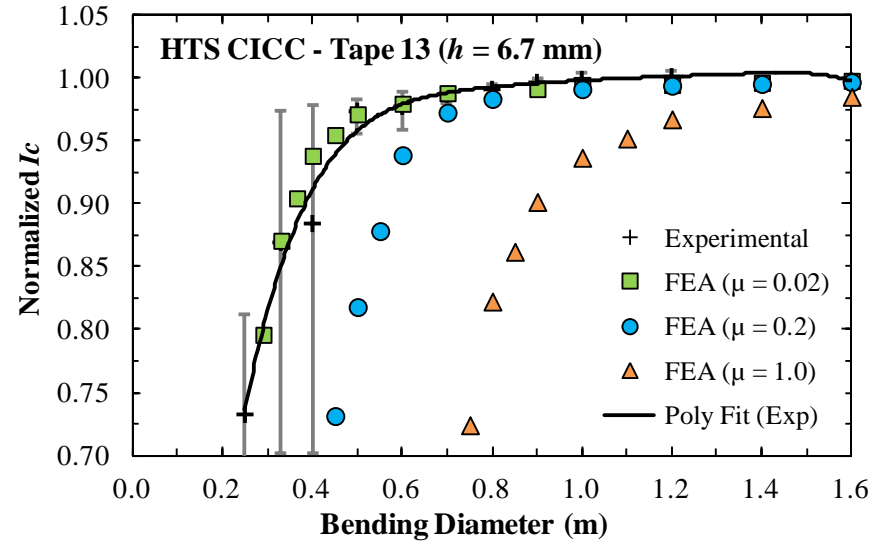
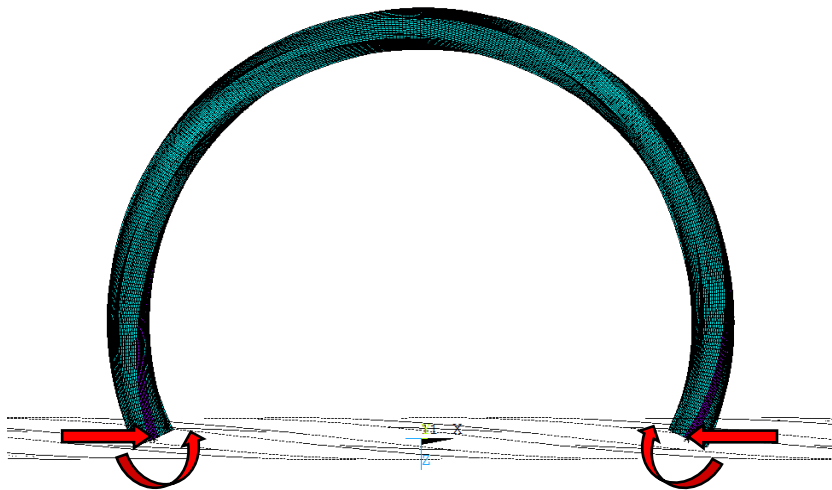
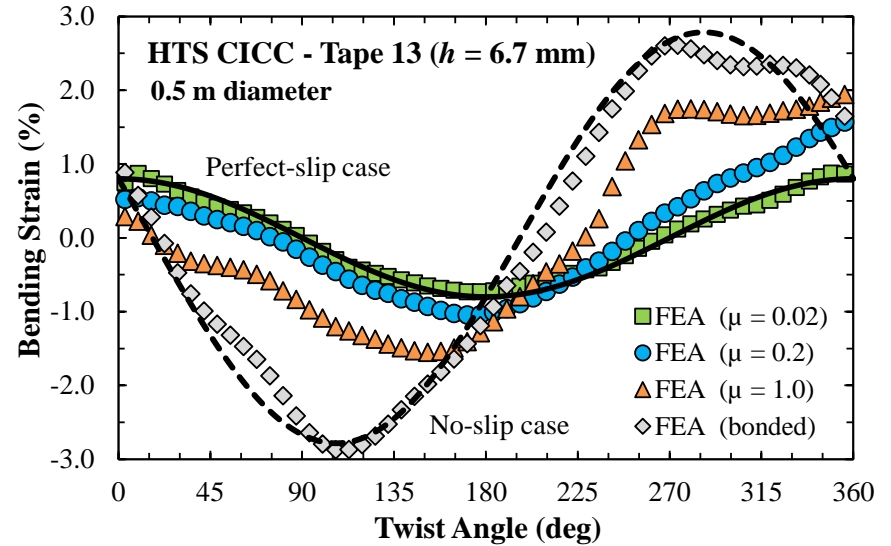
No-slip model

$$\epsilon_b = \frac{\left(\frac{x}{\cos \alpha}\right) \sin \theta + h \cos \theta}{r_o} \cos \alpha$$

Perfect-slip model (PSM)

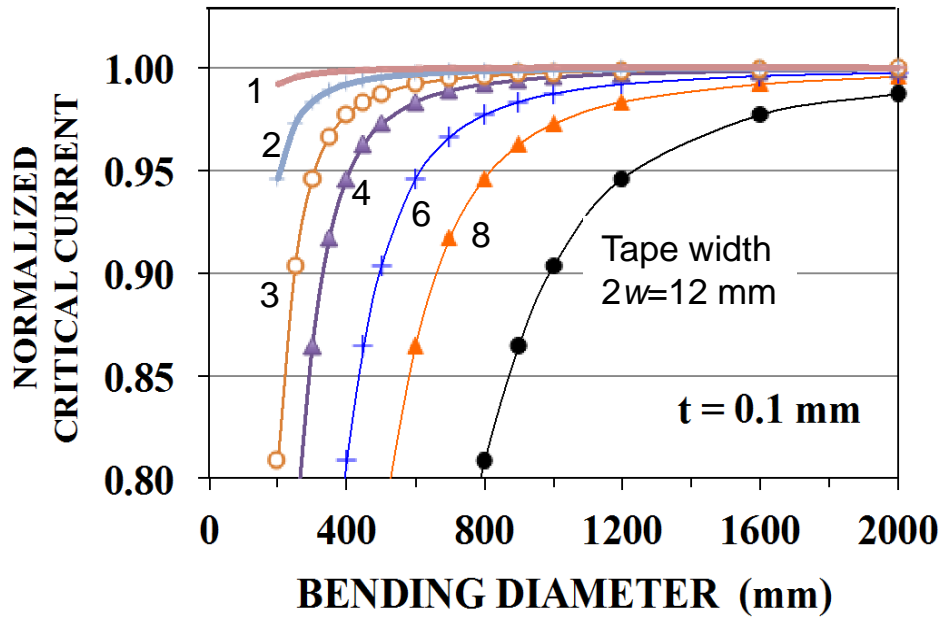


$$\epsilon_b = \frac{x \sin \theta}{r_o}$$





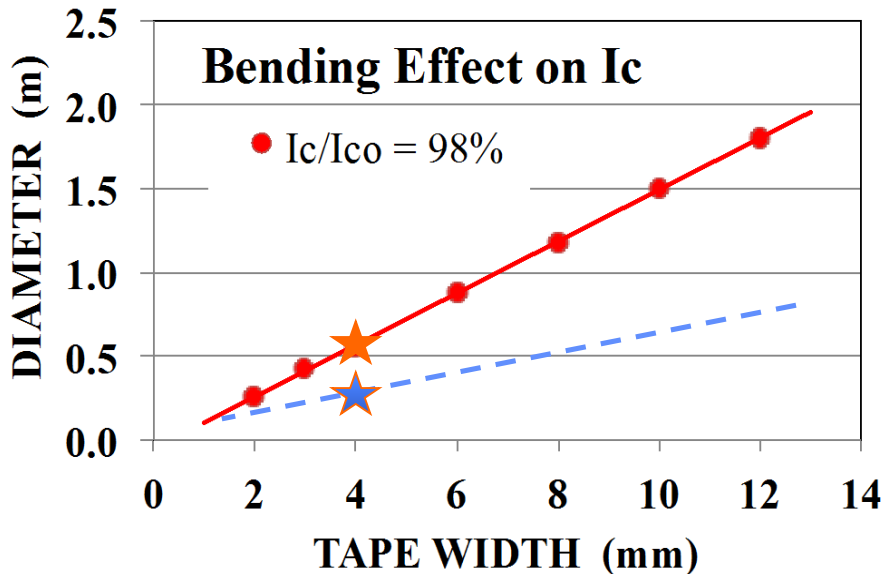
Bending diameters for different tapes width



I_c degradation due to bending
 based on **Perfect-Slip Model**
 (analytical evaluation)

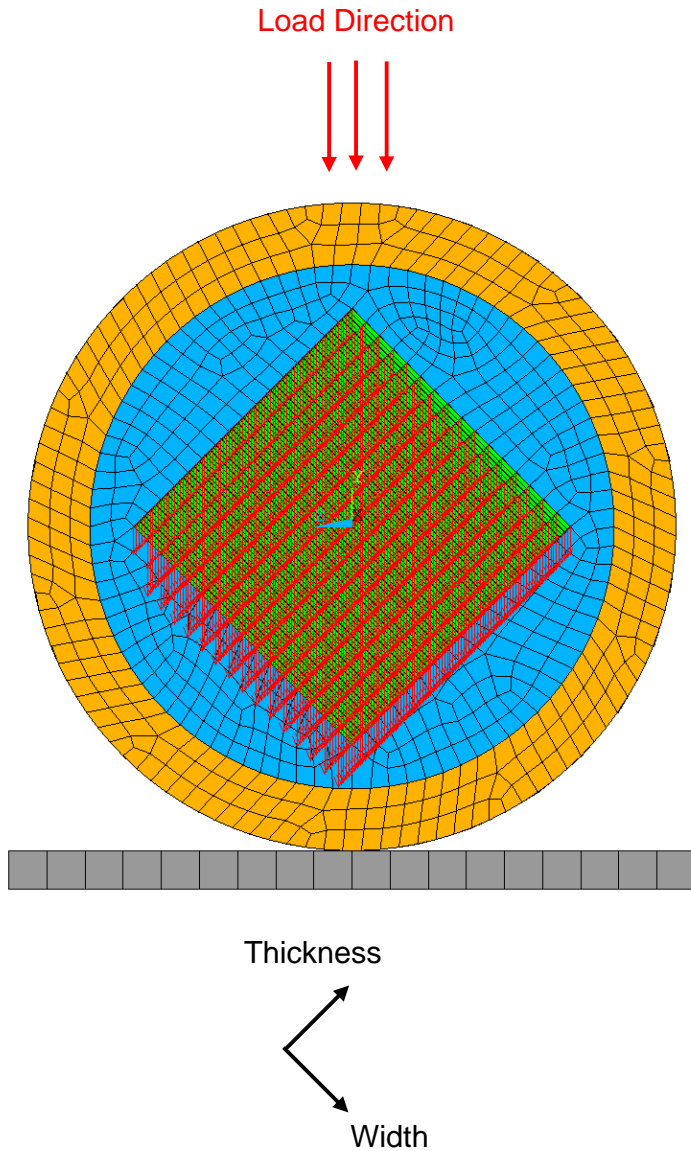
Bending Diameter vs. Tape Width
 (analytical evaluation)

Bending diameter r_o ($0.98 I_c/I_{c0}$) $\approx 150 \cdot 2w$ (mm)
 $2w$ tape width

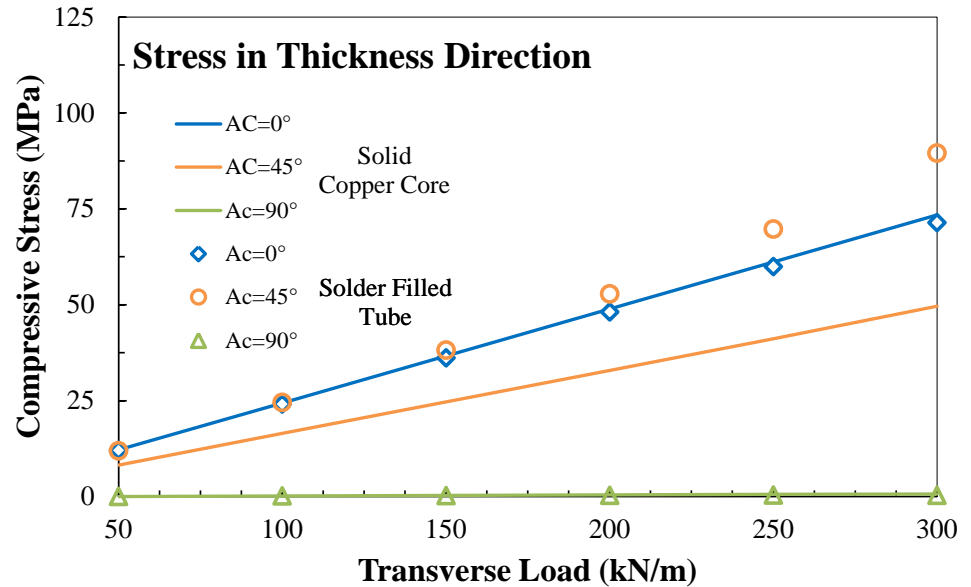
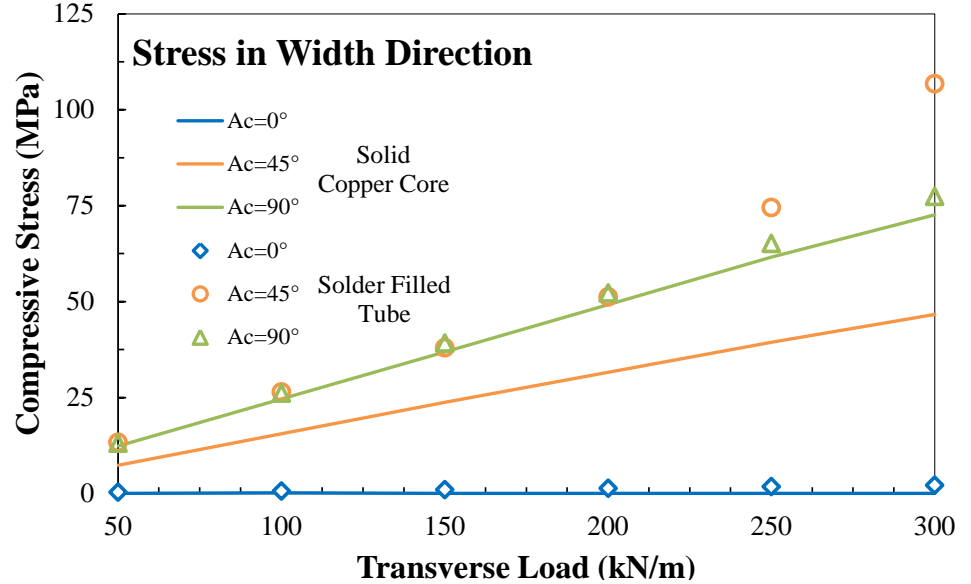




Predicting support structure for large EM loads

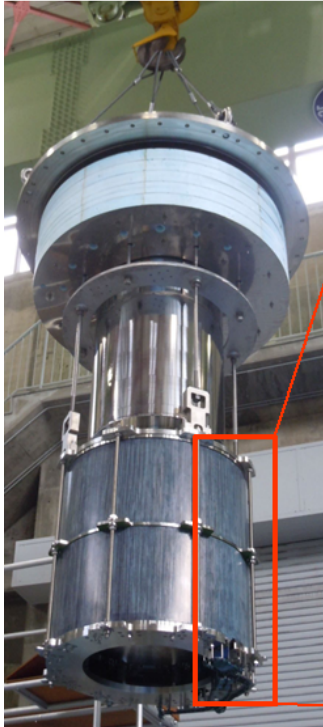


Stress is maximum value of 95% of the elements (stress concentrations were excluded)

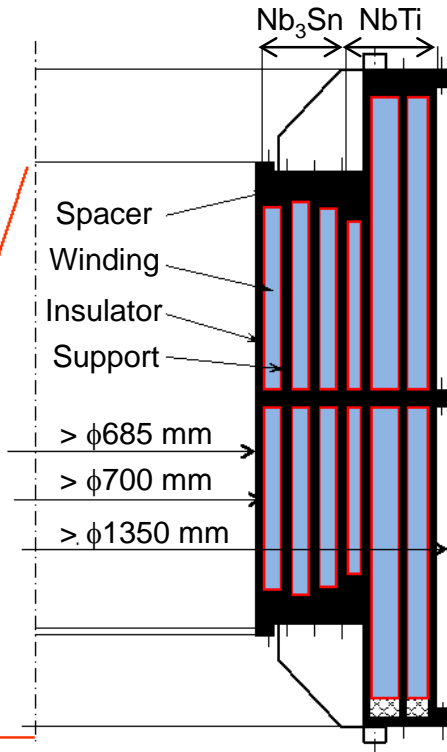




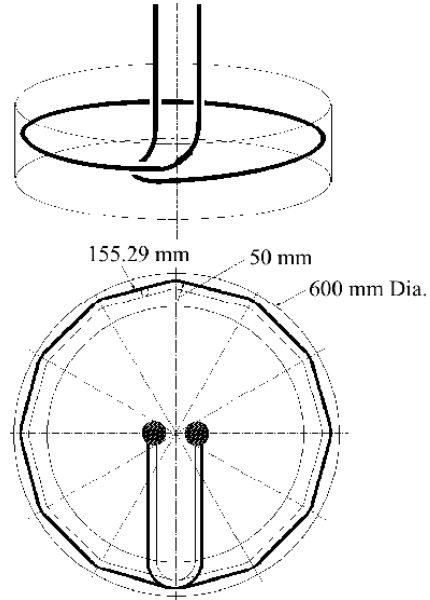
Next TSTC experiment at high fields-NIFS



S. Imagawa

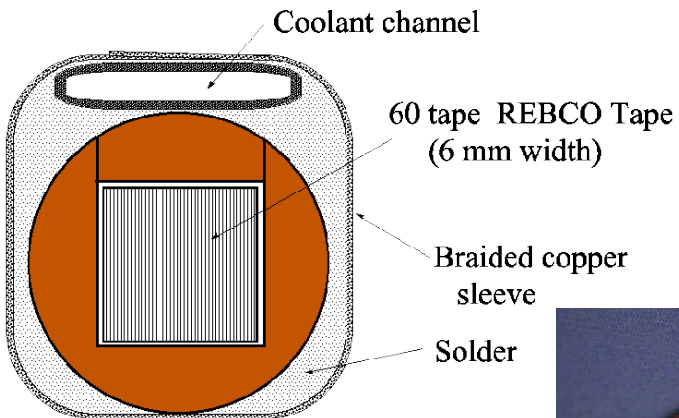


Max. Field: 13 T
Bore: φ700 mm
Sample Current: 50 kA
Temperature: 4-50 K



One turn coil sample
Dodecagon shape


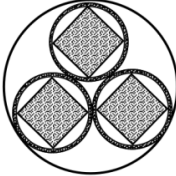
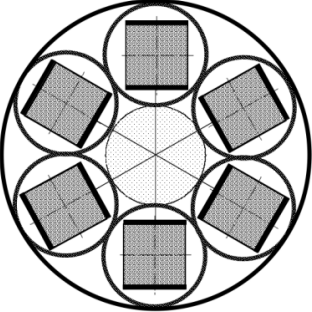
Conductor cross section

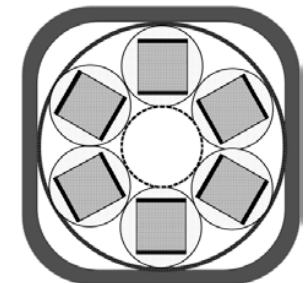




Possible cable configurations

Based on SuperPower SCS4050-AP (2012), 4 mm width, 0.1 mm thickness REBCO tape.
 Tape critical current : **180 A** at **17 T** and **4.2 K**.

Conductor	Tape width (mm)	Tape current (A)	Number of Tapes	Critical Current (kA)	Cable Diameter (mm)	Conductor Cross-Section
Single-stage	4	180	40	7.2	7.4	
	6	270	60	16.2	11.1	
	12	540	120	64.8	22.2	
Triplet	4	180	120 (40 x 3)	22	16	
	6	270	180 (60 x 3)	49	24	
	12	540	360 (120 x 3)	194	48	
Hexa	4	180	240 (40 x 6)	43	23	
	6	270	360 (60 x 6)	97	35	

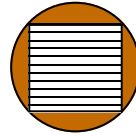


4 mm Tape Hexa CICC
(26 mm x 26 mm)

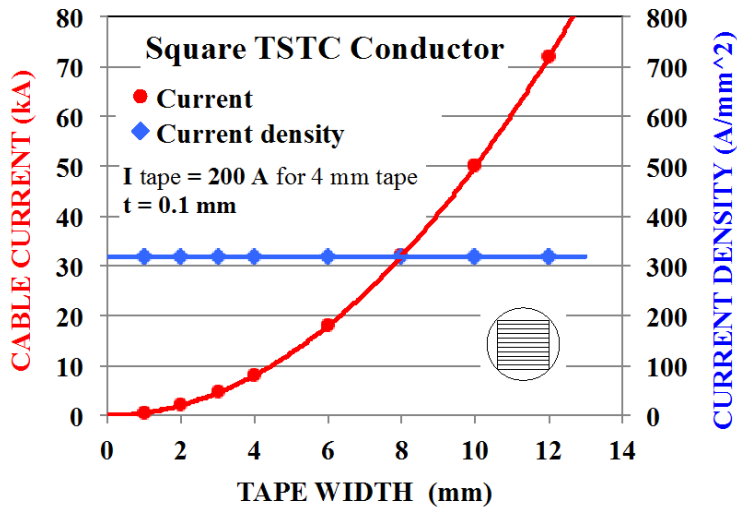


Current and current density vs. width, thickness

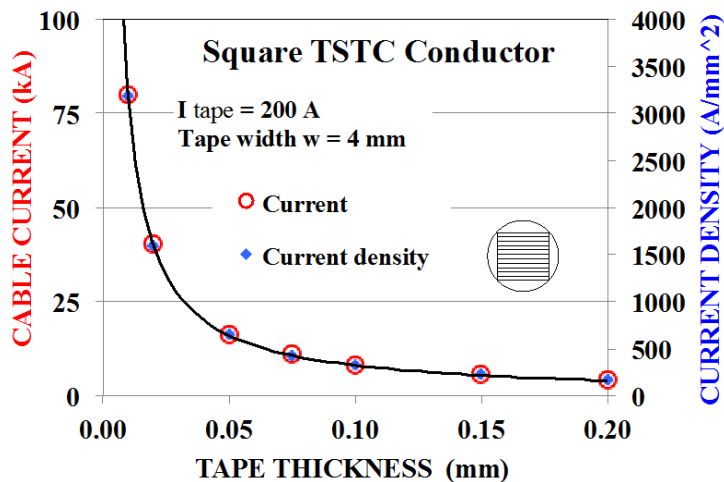
Square TSTC Conductor
 Stabilizer space 36% of total cross-section



Evaluation based on
 4 mm width, 0.1 mm REBCO tape
 Critical current : 200 A



Tape-Width Dependence
 Tape thickness = 0.1 mm

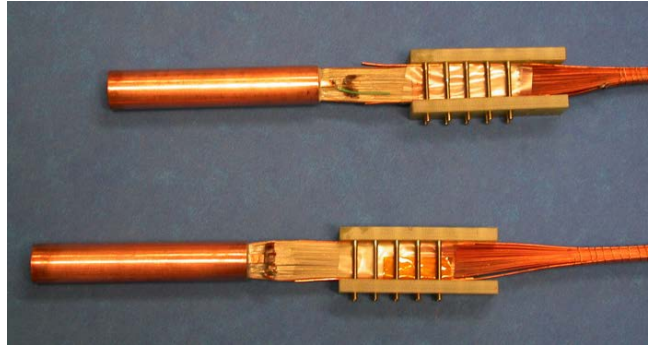
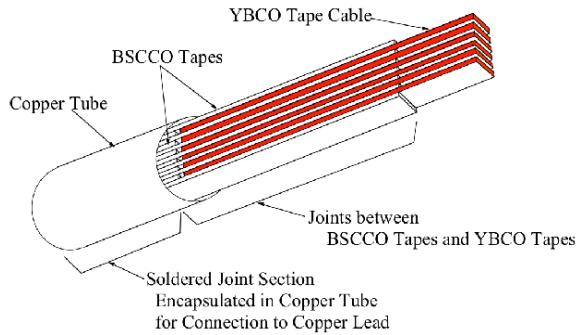


Tape-Thickness Dependence
 Tape width = 4 mm

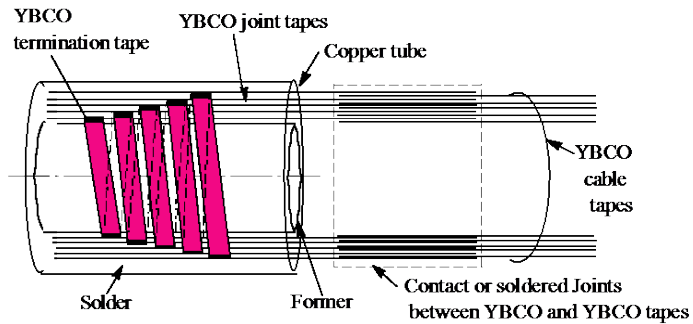


Joints

I. YBCO - BSCCO Termination



II. YBCO - YBCO Termination



III. Folding-Fan Soldered Termination





AC losses characterization

Ohio State University
Prof. Mike Sumption

Various TSTC conductors (30 SuNAM tapes)



(a)

SuNAM (SCN04150-140819-01)

4.1 mm width

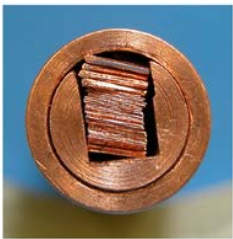
150 μm thickness

Non-magnetic stainless-steel substrate ($>80 \mu\text{m}$)

Tape critical current 200 A at 77 K in self-field
(manufacturer's data).

Conductor length: 203 mm

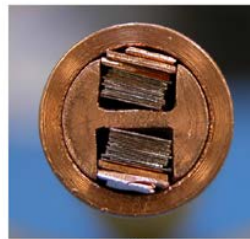
Twist pitch: **200 mm**



(b)



(c)



(d)

Fabricated AC loss test samples of various TSTC conductors (sent to OSU).

(a) Stacked tapes **twisted between copper strips**, encapsulated with a 0.5" OD plexiglass tube.

(b) Tapes **stacked horizontally** in a single helical groove of OFHC rod enclosed in an OFHC sheath (0.5" OD).

(c) Tapes **stacked vertically** in a single helical groove of OFHC rod enclosed in an OFHC sheath (0.5" OD).

(d) Stacked tapes in **two helical grooves** of OFHC rod enclosed in an OFHC sheath (0.5" OD).

These samples **after tests will be soldered** and **sent back to OSU** for the soldered sample tests, in order to investigate solder effects on AC losses.



Future directions and conclusions

- Continue EM studies of cables and use future experiments to validate modeling
 - Use modeling to optimize design of HTS cable options for high field magnets
 - Continue study of joints for HTS cables
 - Comprehensive structural and electromagnetic modeling
 - CICC fabrication development for a long conductor
 - More experiments on cables at high field and 4.2 K are necessary!!! (\$\$\$)
-
- Our **expertise** is the *electromechanical characterization* of *REBCO* (single tape and TSTC) using *experiments and finite element analysis*.
 - The work provides critical information to design and fabricate cables and magnets for HEP/Fusion that are structurally and electromagnetically sound.



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